

AIDA - Academia meets Industry: Advanced interconnections for chip packaging in future detectors

Tuesday, 9 April 2013

Chip stacking through microbump bonding (12:00 - 12:40)

-Conveners: Michael Campbell

time	[id] title	presenter
12:00	[43] The combined technology of TSV and SLID bond	KLUMPP, Armin
12:20	[45] TSV and SLID for planar Silicon Detectors	MACCHIOLO, Anna